

HRG200X

High Rigid Grinder

- Fully Automatic High Rigid Twin Axis Grinder —
- Less-damage Grinding with Shorter Process Time —
- Low Cost —
- High Accuracy —
- Mirror Finish Surface Grinding —





SiC Substrate



LT Substrate

Target Material

Hard-to-Grind materials such as SiC, LT, LN

Target Work

Size : Dia.φ3 to φ8 inch

Actual Result Example

Materials	Size	Grinded thickness	Processing time
SiC	φ6 inch	100 μm	2 min
LT	φ4 inch	100 μm	1 min
LN	φ4 inch	100 μm	1 min

Specification



No	Category	HRG200X
		Full Automatic High Rigid Twin Axis Grinder
1	Appreance	Size: 1540(W) x 2050(D) x 2010(H) mm Weight : 4500 kg
4	Maximum Wafer Size(mm)	200
5	Grinding Wheel Diameter(mm)	250
6	Grinding Wheel Rotation(rpm)	Max. 3,600
7	Work Spindle Axis Rotation(rpm)	Max. 800
8	Grinding Wheel Spindle Power(kW)	6.3
9	Total Thickness Variation : TTV(μm)	1
10	Wafer to Wafer Thickness Variation : WTW(μm)	±1

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C-63-844-E-1712_3